

## **REMARKS**

### **Drawings**

As FIG. 23 has been approved by the Examiner, it is being submitted directly to the Official Draftsperson.

### **Rejections under 35 U.S.C. 112, first paragraph**

Claims 3-15, 28, and 29 were rejected under 35 U.S.C. 112, first paragraph. The Examiner asserted that 24 and 30 are substrates interposed between the first and second integrated circuits. The Examiner's point is mute as Applicants have amended independent claims 3 and 6 to state that "die attach material is interposed between the first integrated circuit and the second integrated circuit". The specification clearly has support for this (see page 3, line 25 and page 4, lines 17-18 of the specification).

### **Rejections under 35 U.S.C. 102 and 103**

Applicants have amended the independent claims 1, 3, and 6 to expressly state that "die attach material is interposed between the first integrated circuit and the second integrated circuit". This is NOT taught or even suggested by Shin (U.S. Patent 6,515,356 B1).

The other dependent claims are allowable for at least the same reasons as given for the independent claims.

New claims 30 and 31 are submitted herein.

Applicants believe the application is in condition for allowance which action is respectfully solicited. Please contact me if there are any issues regarding this communication or the current Application.

Respectfully submitted,

SEND CORRESPONDENCE TO:

Motorola, Inc.  
Law Department

Customer Number: 23125

By: 

Daniel D. Hill

Attorney of Record

Reg. No.: 35,895

Telephone: (512) 996-6839

Fax No.: (512) 996-6854